

DESCRIPTION

The IS121 series consists of an infrared light emitting diode optically coupled to an NPN silicon photo transistor in a space efficient Mini Flat Package.

FEATURES

- Low Profile Package
- AC Isolation Voltage 3750V_{RMS}
- Wide Operating Temperature Range -55°C to +110°C
- RoHS Compliant
- UL File E91231 model "FPT1", "FPT2"

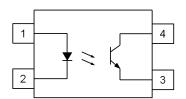
APPLICATIONS

- Computer Terminals
- **Industrial System Controllers**
- Measuring Instruments
- Signal Transmission between Systems of Different Potentials and Impedance

ORDER INFORMATION

Available in Tape and Reel with 3000 pieces per reel





- Anode
- 2 Cathode
- Emitter
- Collector

ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device.

Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

Input

| Forward Current | 50mA |
|-------------------------------------|-------|
| Peak Forward Current (100µs, 100Hz) | 1A |
| Reverse Voltage | 6V |
| Power Dissipation | 70mW |
| Junction Temperature | 125°C |

Output

Collector to Emitter Voltage V_{CEO} 80V Emitter to Collector Voltage V_{ECO} 6V 50mA Collector Current Power Dissipation 150mW 125°C Junction Temperature

Total Package

3750V_{RMS} Isolation Voltage 170mW **Total Power Dissipation**

-55 to +110°C Operating Temperature Storage Temperature -55 to +150°C

Lead Soldering Temperature (10s) 260°C

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

INPUT

| Parameter | Parameter Symbol Test Condition | | Min | Тур. | Max | Unit |
|----------------------------------|---------------------------------|--------------------|-----|------|-----|------|
| Forward Voltage | V_F $I_F = 20 mA$ | | | 1.2 | 1.4 | V |
| Reverse Current I_R $V_R = 4V$ | | | | 10 | μΑ | |
| Terminal Capacitance | C_{t} | V = 0V, $f = 1KHz$ | | 30 | 250 | pF |

OUTPUT

| Parameter | Symbol | Test Condition | Min | Тур. | Max | Unit |
|--|------------------------------|---|-----|------|-----|------|
| Collector-Emitter Breakdown Voltage | $\mathrm{BV}_{\mathrm{CEO}}$ | $I_C = 0.1 \text{mA}, I_F = 0 \text{ mA}$ | 80 | | | V |
| Emitter-Collector Breakdown Voltage | $\mathrm{BV}_{\mathrm{ECO}}$ | $I_E=10\mu A,I_F=0mA$ | 6 | | | V |
| Collector-Emitter Dark Current | I_{CEO} | $V_{CE}=20V,I_F=0mA$ | | | 100 | nA |

COUPLED

| Parameter Symbol | | Test Condition | Condition Min | | Max | Unit |
|---|----------------------|---|---------------|-----|-----|------|
| Current Transfer Ratio C | | $I_F = 5mA$, $V_{CE} = 5V$ | 50 | | 600 | % |
| | | Optional CTR Grades | | | | |
| | | IS121A | 80 | | 160 | |
| | | IS121B | 130 | | 260 | |
| | | IS121C | 200 | | 400 | |
| | | IS121D | 300 | | 600 | |
| Collector-Emitter Saturation Voltage | V _{CE(sat)} | $I_F = 20 \text{mA}, I_C = 1 \text{mA}$ | | | 0.2 | V |
| Floating Capacitance | C_{f} | V = 0V, $f = 1MHz$ | | 0.6 | 1 | pF |
| Output Rise Time | t _r | $V_{CE} = 2V$ $Ic = 2mA$ | | 4 | 18 | μs |
| Output Fall Time | $t_{ m f}$ | $R_{L} = 100\Omega$ | | 3 | 18 | μs |

ISOLATION

| Parameter | Symbol | Symbol Test Condition | | Тур. | Max | Unit |
|----------------------|---------------|---|--------------------|--------------------|-----|-----------|
| Isolation Voltage | $V_{\rm ISO}$ | RH = 40% to 60%, $t = 1$ min | 3750 | | | V_{RMS} |
| Isolation Resistance | $R_{\rm ISO}$ | $RH = 40\% \text{ to } 60\% \\ V_{I-O} = 500 VDC$ | 5x10 ¹⁰ | 1x10 ¹¹ | | Ω |

Measured with input leads shorted together and output leads shorted together.



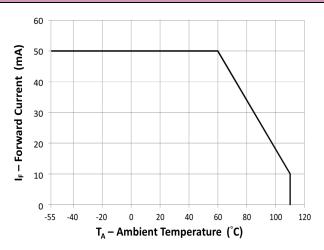


Fig 1 Forward Current vs Ambient Temperature

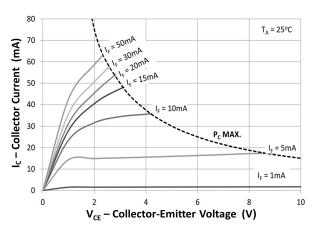


Fig 3 Collector Current vs Collector-Emitter Voltage

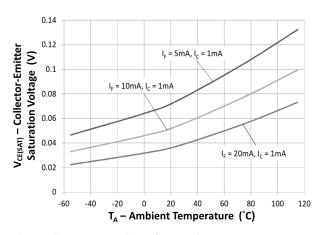


Fig 5 Collector-Emitter Saturation Voltage vs Ambient Temperature

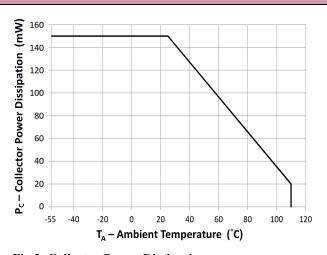


Fig 2 Collector Power Dissipation vs Ambient Temperature

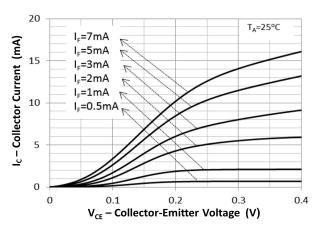


Fig 4 Collector Current vs Collector-Emitter Saturation Voltage

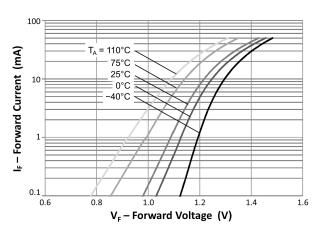


Fig 6 Forward Current vs Forward Voltage



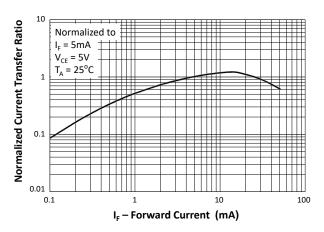


Fig 7 Normalized Current Transfer Ratio vs Forward Current

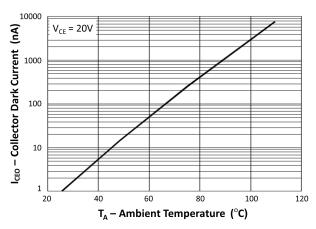


Fig 9 Collector Dark Current vs Ambient Temperature

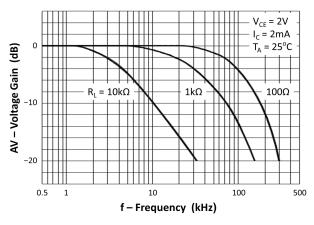


Fig 11 Frequency Response

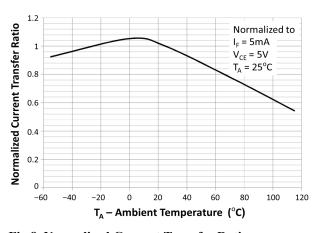


Fig 8 Normalized Current Transfer Ratio vs Ambient Temperature

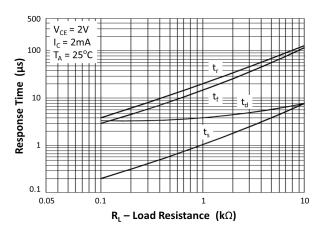
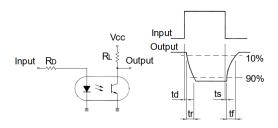
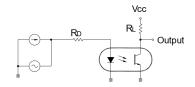


Fig 10 Response Time vs Load Resistance



Response Time Test Circuit



Frequency Response Test Circuit



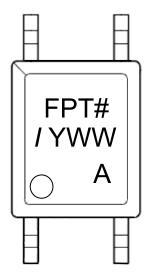
ORDER INFORMATION

| | IS121 | | | | | |
|------------------|----------------------------------|---------------------------|-------------------|--|--|--|
| After PN | PN | Description | Packing quantity | | | |
| None | IS121 | Surface Mount Tape & Reel | 3000 pcs per reel | | | |
| Any CTR Grade | IS121A, IS121B IS121C, IS121D | Surface Mount Tape & Reel | 3000 pcs per reel | | | |

NOTE: Multiple Grades may be supplied to meet the requested specification.

DEVICE MARKING

Example: IS121A



FPT# Device Part Number where "#" is internal control number

which can be "1" or '2"

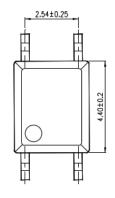
A CTR Grade

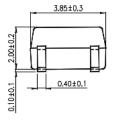
I Isocom

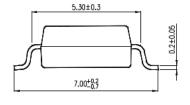
Y 1 digit Year code WW 2 digit Week code



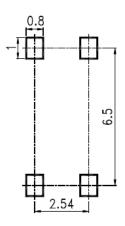
PACKAGE DIMENSIONS (mm)





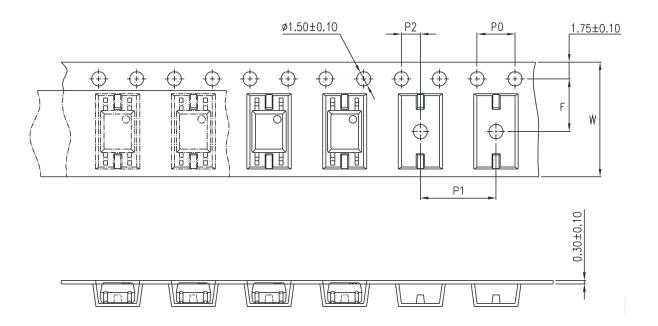


RECOMMENDED SOLDER PAD LAYOUT (mm)





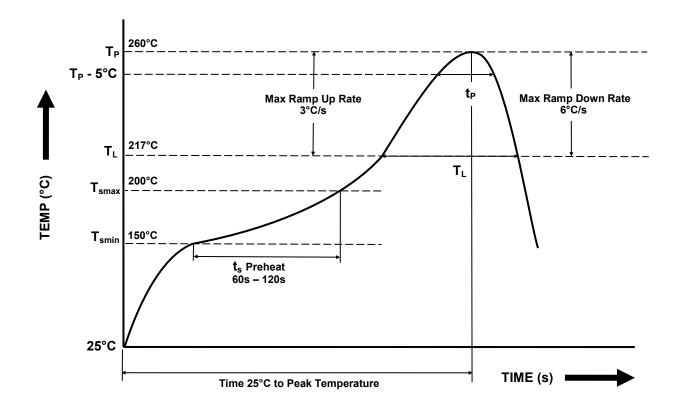
TAPE AND REEL PACKAGING



| Description | Symbol | Dimension mm (inch) |
|---|----------------|------------------------|
| Tape Width | W | 12 ± 0.3 (0.47) |
| Pitch of Sprocket Holes | P ₀ | 4 ± 0.1 (0.157) |
| Distance of Compartment to Sprocket Holes | F | 5.5 ± 0.1 (0.217) |
| Distance of Compartment to Sprocket Holes | P ₂ | 2 ± 0.1 (0.079) |
| Distance of Compartment to Compartment | P ₁ | 8 ± 0.1 (0.315) |



IR REFLOW SOLDERING TEMPERATURE PROFILE One Time Reflow Soldering is Recommended. Do not immerse device body in solder paste.



| Profile Details | Conditions |
|---|--|
| $ \begin{array}{l} \textbf{Preheat} \\ \textbf{- Min Temperature } (T_{SMIN}) \\ \textbf{- Max Temperature } (T_{SMAX}) \\ \textbf{- Time T}_{SMIN} \ \text{to T}_{SMAX} \left(t_{s} \right) \end{array} $ | 150°C 200°C 60s - 120s |
| $\begin{tabular}{lll} \textbf{Soldering Zone} \\ &- \mbox{Peak Temperature } (T_P) \\ &- \mbox{Time at Peak Temperature} \\ &- \mbox{Liquidous Temperature } (T_L) \\ &- \mbox{Time within } 5^{\circ}\mbox{C of Actual Peak Temperature } (T_P - 5^{\circ}\mbox{C}) \\ &- \mbox{Time maintained above } T_L (t_L) \\ &- \mbox{Ramp Up Rate } (T_L \mbox{ to } T_P) \\ &- \mbox{Ramp Down Rate } (T_P \mbox{ to } T_L) \\ \end{tabular}$ | 260°C 10s max 217°C 30s max 60s - 100s 3°C/s max 6°C/s max |
| Average Ramp Up Rate (T _{smax} to T _P) | 3°C/s max |
| Time 25°C to Peak Temperature | 8 minutes max |



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